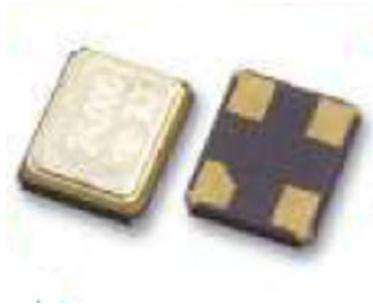


X25F



Description:

- Ultra-Miniature Size
- Mobile Communications Applications
- Highly Precise
- Bluetooth
- Ceramic Package
- Wireless Lan
- Tape and Reel
- Office Automation
- Reflow Soldering
- Audio Video

Performance Characteristics

Parameter		X32F
Frequency Range	F ₀	12.000MHz~54.000MHz
Mode of Vibration		Fundamental
Resonance Resistance	R _r	30 to 150 Ohms Max
Frequency Tolerance (at 25°C)		±5×10 ⁻⁶ ~±30×10 ⁻⁶
Storage Temperature Range	T _{STG}	-55°C~+125°C
Shunt Capacitance	C ₀	3pF Max
Load Capacitance	CL	8pF~50pF or Series
Insulation Resistance	IR	>500M DC/100V±10V
Drive Level	DL	0.01mW~0.1mW
Aging	Fa	±2×10 ⁻⁶ /year

Frequency Stability Over Temperature Range

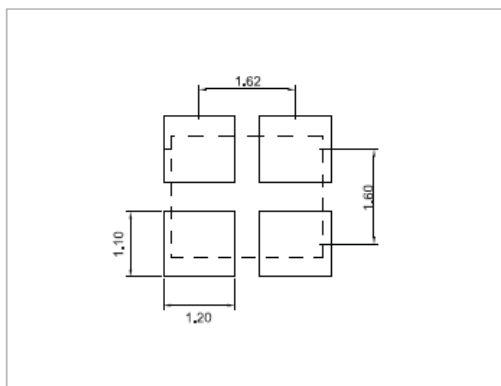
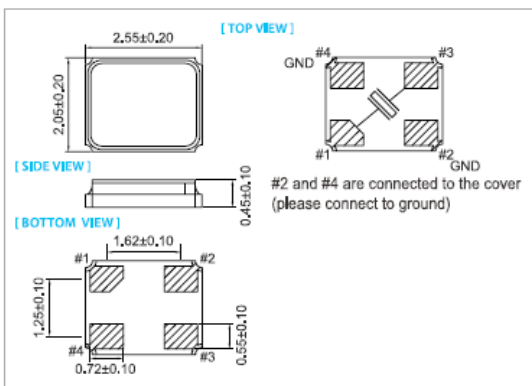
Temperature Range	Frequency Stability				
	O:±5×10 ⁻⁶	P:±15×10 ⁻⁶	Q:±20×10 ⁻⁶	S:±30×10 ⁻⁶	T:±50×10 ⁻⁶
A: 0°C~+50°C	●	●	●	●	●
B:-10°C~+60°C	●	●	●	●	●
C:-20°C~+70°C	●	●	●	●	●
G:-40°C~+85°C		●	●	●	●

Frequency Stability over wide Temp. Range

H:-40°C~+105°C +/-15ppm TO +/-50ppm Available

I:-40°C~+125°C +/-30ppm TO +/-50ppm Available

Outline Drawing (mm)



PAD NO.	CONNECTION
#1	INPUT
#2	GND
#3	OUTPUT
#4	GND